

## REWORK METHODS FOR LEAD FREE BGA/CGA

### ABSTRACT OF THE DISCLOSURE

5 A method and apparatus are provided for reworking electronic component assemblies where the components are joined by solder interconnections. A cutting device employing a heated wire, blade or other cutting element is forced against and through the solder interconnections to sever the interconnections. A preferred cutting device employs moving the cutting element transverse to the solder interconnections to also provide a sawing action to the solder interconnections. Another cutting device  
10 employs a water jet to provide a high pressure stream of water that cuts and severs the solder interconnections.

For additional information, see the full disclosure.